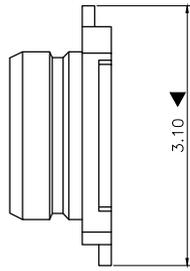
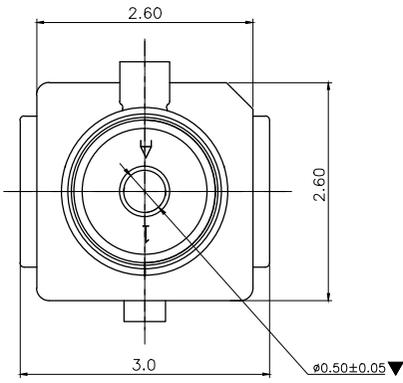
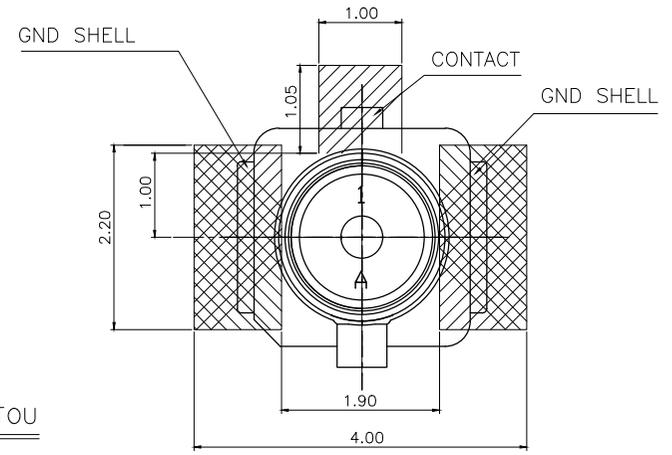


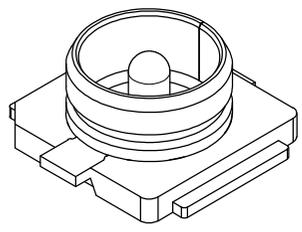
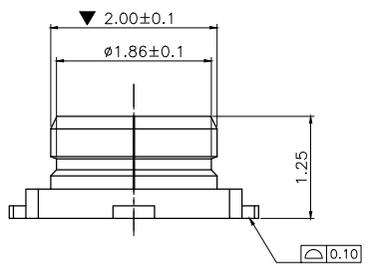
REV	ECN NO	DESCRIPTION	DATE	APPD
A		NEW RELEASE	2019.05.24	曾庆勇



RECOMMENDED PCB LAYTOU
(TOLERANCE: ± 0.05)

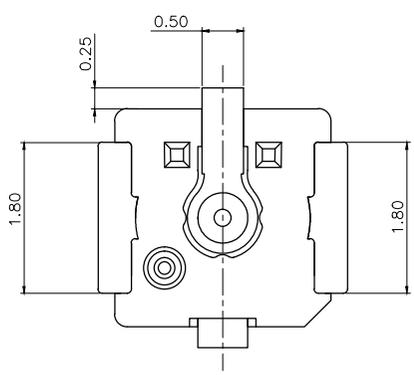


RECOMMENDED PCB LAYTOU
(TOLFRANCF: ± 0.05)



NOTE:

- HOUSING MATERIAL: THERMOPLASTIC, BLACK, UL 94V-0;
CONTACT MATERIAL: COPPER ALLOY;
GOLD PLATED: CONTACT AREA & SOLDER AREA
SHELL MATERIAL: COPPER ALLOY;
GOLD PLATED: CONTACT AREA&SOLDER AREA
- PERFORMANCE:
 - CONTACT RESISTANCE: 20mOHM Max.
 - DIELECTRIC WITHSTANDING VOLTAGE: 100V AC FOR 1MINUTE;
 - INSULATION RESISTANCE: 500MOHM Min.
- COPLANARITY: 0.1mm Max.
- APPLIED TO IR SOLDERING RROCESS.
- DIMEN SIONS MARKED ▼ AS THE FOCUS CONTROL SIZE



EXTEND USE		TITLE				
RF1 BOARD CONN		RF1 BOARD CONN				
UNIT mm		MATERIAL		APPD	DWG NO	
GENERAL TOLERANCE (M)		2019.05.24		石永涛	19.002A7	
DIMENSION		QTY		CHD	P/N:	
0. /	ANGLES	2019.05.24		朱春辉	19.002A7-0001R0	
.0 ±0.15	0. ±3.0°	FINISHED		DRN	SHEET	
.00 ±0.10	.0 ±2.0°	2019.05.24		彭龙芳	SCALE	REV
.000 /	.00 ±1.0°				1/1	A